



# P-Channel 1.8 V (G-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>c</sup>	Q <sub>g</sub> (Typ.)	
	0.112 at V <sub>GS</sub> = - 4.5 V	- 1.6		
- 8	0.160 at V <sub>GS</sub> = - 2.5 V	- 1.6	3.67 nC	
	0.210 at V <sub>GS</sub> = - 1.8 V	- 1.6		

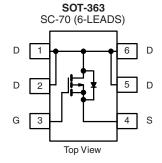
### **FEATURES**

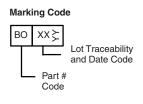
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



## **APPLICATIONS**

• Load Switch for Portable Devices





Ordering Information: Si1405BDH-T1-E3 (Lead (Pb)-free)

Si1405BDH-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V <sub>DS</sub>	- 8	V		
Gate-Source Voltage		V <sub>GS</sub>			± 8
	T <sub>C</sub> = 25 °C		-1.6 <sup>c</sup>		
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>a, b</sup>	T <sub>C</sub> = 70 °C		- 1.6 <sup>c</sup>		
Continuous Drain Current (1 <sub>J</sub> = 150 °C) <sup>3, 3</sup>	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 1.6 <sup>a, b, c</sup>		
	T <sub>A</sub> = 70 °C		- 1.6 <sup>a, b, c</sup>	Α	
Pulsed Drain Current (10 µs Pulse Width)		I <sub>DM</sub>	- 8 <sup>c</sup>		
Continuous Source-Drain Diode Current <sup>a, b</sup>	T <sub>C</sub> = 25 °C	1	- 1.6 <sup>c</sup>		
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	- 1.47 <sup>a, b</sup>		
	T <sub>C</sub> = 25 °C		2.27		
Maximum Power Dissipation <sup>a, b</sup>	T <sub>C</sub> = 70 °C		1.45	w	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	1.47 <sup>a, b</sup>	VV	
	T <sub>A</sub> = 70 °C		0.95 <sup>a, b</sup>		
Operating Junction and Storage Temperature Rar	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		
Soldering Recommendations (Peak Temperature)		260			

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a, d</sup>	t ≤ 5 s	R <sub>thJA</sub>	70	85	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	44	55	C/VV

## Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s
- c. Package limited.
- d. Maximum under steady state conditions is 125 °C/W.

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SPECIFICATIONS T <sub>J</sub> = 25 °C	unless oth	nerwise noted					
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 8			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 5.4		m)//ºC	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	l <sub>D</sub> = - 250 μA		1.98		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 0.45		- 0.95	V	
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = -8 V			- 100	nA	
Zoro Coto Voltago Designo	I <sub>DSS</sub>	$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}$			- 1		
Zero Gate Voltage Drain Current		V <sub>DS</sub> = -8 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			- 10	- μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 8			Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -2.8 \text{ A}$		0.091	0.112		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = -2.5 \text{ V}, I_D = -2.3 \text{ A}$		0.132	0.160	Ω	
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 0.5 A		0.171	0.205	1	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 4 V, I <sub>D</sub> = - 2.8 A		4.8		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			305		pF	
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> = - 4 V, V <sub>GS</sub> = 0 V, f = 1 MHz		108			
Reverse Transfer Capacitance	C <sub>rss</sub>			66			
Total Gate Charge	$Q_g$	V <sub>DS</sub> = - 4 V, V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 2.8 A		3.67	5.5	nC	
Gate-Source Charge	$Q_{gs}$			0.61			
Gate-Drain Charge	$Q_{gd}$			0.98			
Gate Resistance	$R_g$	f = 1 MHz		6.3		Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			10	15		
Rise Time	t <sub>r</sub>	$V_{DD} = -4 \text{ V}, R_L = 1.78 \Omega$ $I_D \cong -2.25 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		26	39	- ns	
Turn-Off Delay Time	t <sub>d(off)</sub>			16	24		
Fall Time	t <sub>f</sub>			7	10.5		
Drain-Source Body Diode Characterist	ics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			- 1.6	A	
Pulse Diode Forward Current	I <sub>SM</sub>				- 8		
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 1.4 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			23	35	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = - 1.4 A, dl/dt = 100 A/μs, T <sub>J</sub> = 25 °C		5.8	8.7	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			6		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			17			

#### Notes

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

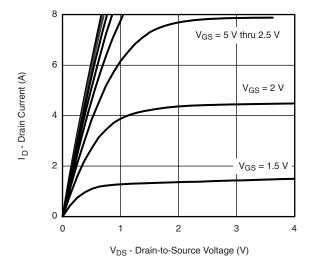
a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

b. Guaranteed by design, not subject to production testing.

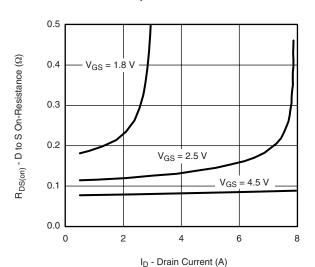




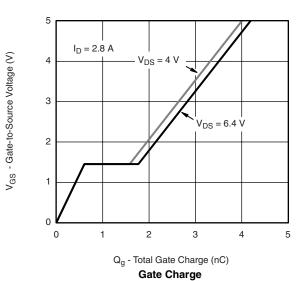
## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Output Characteristics



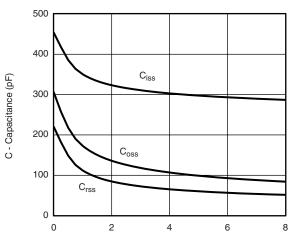
On-Resistance vs. Drain Current and Gate Voltage



3.0 2.4 I<sub>D</sub> - Drain Current (A) 1.8 T<sub>J</sub> = 25 °C 1.2  $T_J = 125$  °C 0.6 T<sub>J</sub> = - 55 °C 0.0 0.0 0.4 0.8 1.2 1.6 2.0

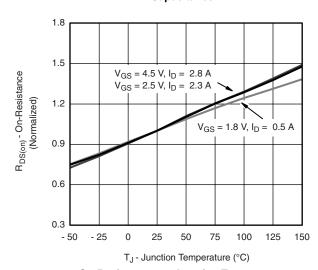
 $V_{\mbox{\footnotesize GS}}$  - Gate-to-Source Voltage (V)





V<sub>DS</sub> - Drain-to-Source Voltage (V)

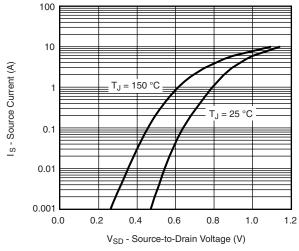
### Capacitance



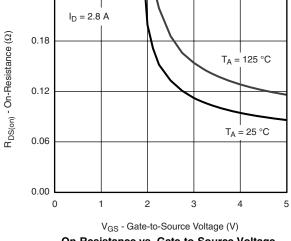
On-Resistance vs. Junction Temperature

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# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

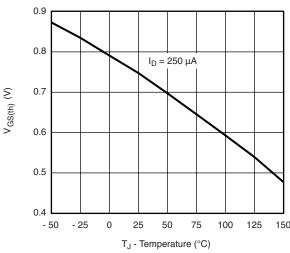


## Source-Drain Diode Forward Voltage

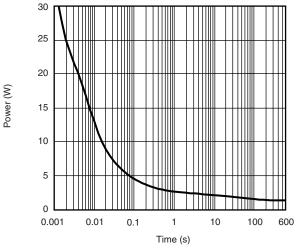


0.24

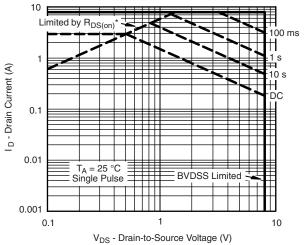
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



Single Pulse Power, Junction-to-Ambient

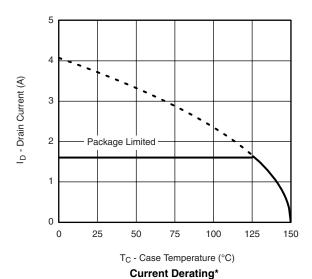


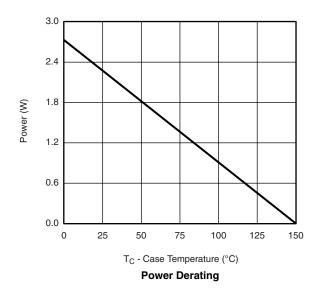
 $^{\star}$   $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

Safe Operating Area, Junction-to-Ambient

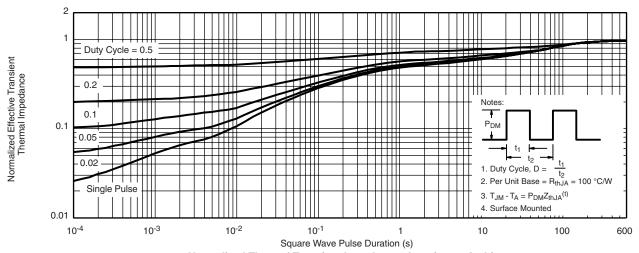


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Ambient

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